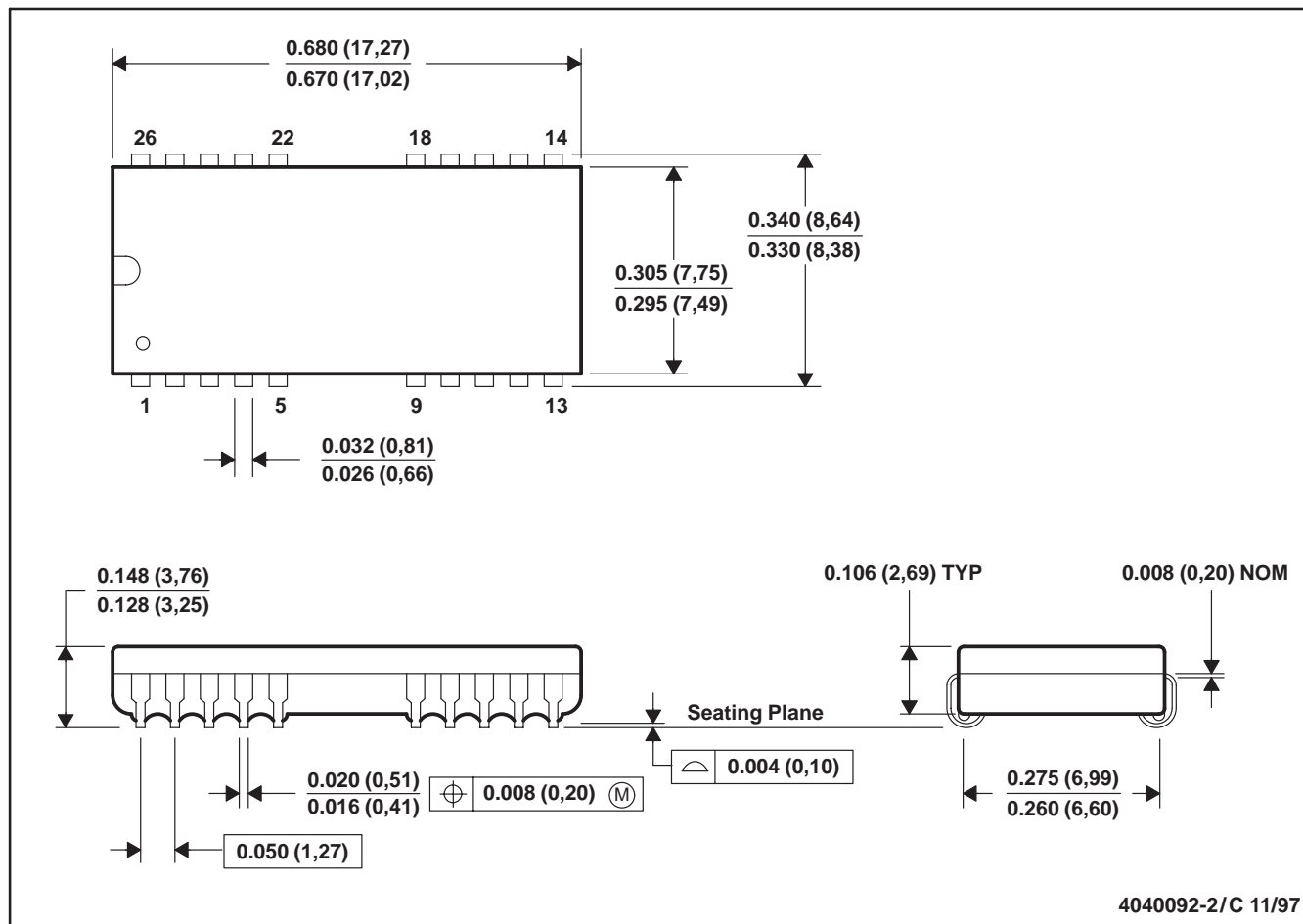


DJ (R-PDSO-J20/26)

PLASTIC SMALL-OUTLINE J-LEAD PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Plastic body dimensions do not include mold protrusion. Maximum mold protrusion is 0.006 (0,15) per side.

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